

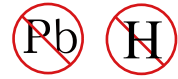


SEMICONDUCTOR

DATA SHEET

YSSR05

LOW CAPACITANCE TVS DIODE ARRAY



APPLICATIONS

- ◆ High-Speed Data Lines
- ◆ Microprocessor Based Equipment
- ◆ LAN/WAN Equipment
- ◆ Notebooks, Desktops, and Servers
- ◆ Instrumentation
- ◆ 10/100 Ethernet

IEC COMPATIBILITY

- ◆ IEC61000-4-2 (ESD) $\pm 15\text{kV}$ (air), $\pm 8\text{kV}$ (contact)
- ◆ IEC61000-4-4 (EFT) 40A (5/50 η s)

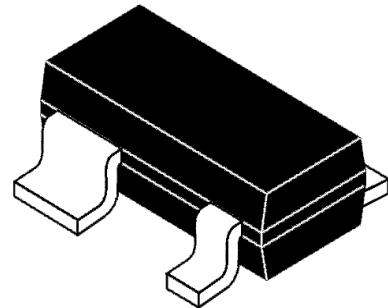
FEATURES

- ◆ 300 Watts Peak Pulse Power per Line ($t_p=8/20\mu\text{s}$)
- ◆ Protects Two High-Speed I/O Lines
- ◆ Low Capacitance For High-Speed Interfaces
- ◆ Low Clamping And Operating Voltage
- ◆ RoHS Compliant

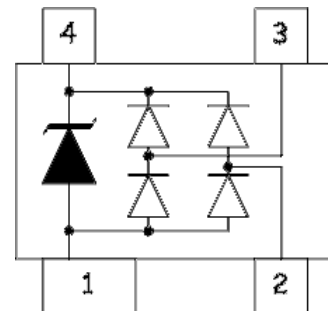
MECHANICAL CHARACTERISTICS

- ◆ SOT-143 Package
- ◆ Molding Compound Flammability Rating : UL 94V-0
- ◆ Weight 9.0 Milligrams (Approximate)
- ◆ Quantity Per Reel : 3,000pcs
- ◆ Reel Size : 7 inch
- ◆ Lead Finish : Lead Free

SOT-143



PIN CONFIGURATION

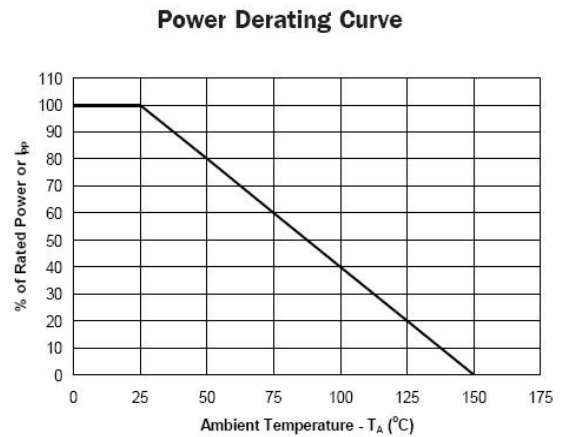
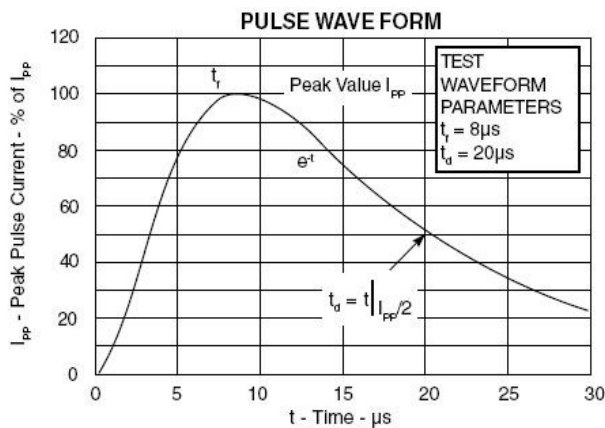


DEVICE CHARACTERISTICS

YSSR05

MAXIMUM RATINGS (@ 25°C Unless Otherwise Specified)			
PARAMETER	SYMBOL	VALUE	UNITS
Peak Pulse Power (tp=8/20μs waveform)	P _{PP}	300	Watts
Lead Soldering Temperature	T _L	260 (10 sec.)	°C
Operating Temperature Range	T _J	-55 ~ 150	°C
Storage Temperature Range	T _{STG}	-55 ~ 150	°C

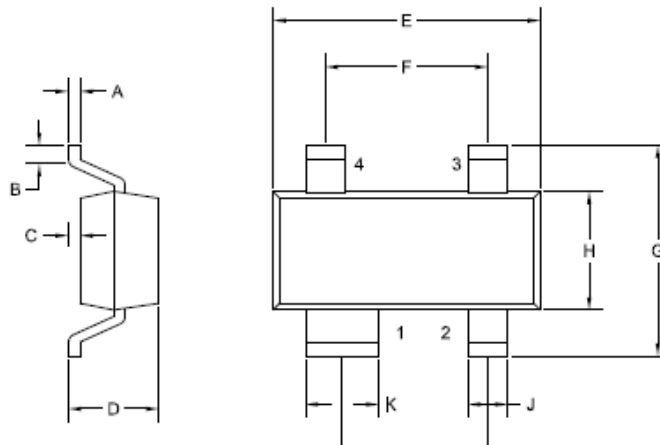
ELECTRICAL CHARACTERISTICS PER LINE (@ 25°C Unless Otherwise Specified)									
PART NUMBER	DEVICE MARKING	V _{RWM} (V) (max.)	V _B (V) (min.)	I _T (mA)	V _C @1A (max.)	V _C (max.) (@A)		I _R (μA) (max.)	C _T (pF) (typ.)
YSSR05	BSL3	5	6	1	9.8	25	3	1	1



PACKAGE OUTLINE & DIMENSIONS

YSSR05

Mechanical Drawing



DIMENSIONS				
SYMBOL	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.003	0.006	0.08	0.15
B	0.006	-	0.15	-
C	-	0.005	-	0.13
D	-	0.045	-	1.14
E	0.110	0.120	2.79	3.04
F	0.075		1.90	
G	-	0.098	-	2.50
H	0.047	0.055	1.19	1.40
J	0.014	0.020	0.36	0.50
K	0.030	0.037	0.76	0.93
L	0.067		1.70	

* SOLDERING FOOTPRINT

